


## ■ Provided Touchstone Model

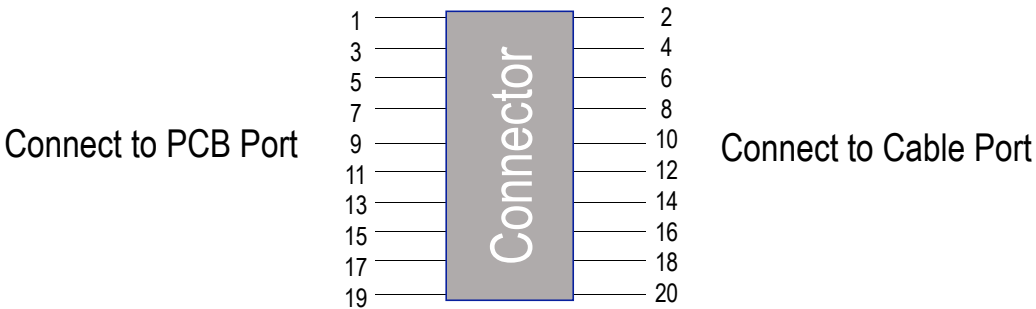
Image	Product name	Pitch [mm]	Mating	Remarks
	CABLINE®-VS II	0.5	Horizontal	<ul style="list-style-type: none"> <li>▪ High Speed Transmission</li> <li>▪ EMI Reduction</li> </ul>

Model Type	Pin assignment	Cable Length (mm)	Cable Zo (Ohm)	AWG	File name
<b>Harness</b> (Connector and Cable model)	All Signal	100	45	36	VSII_hns_100mm_45ohm_36.s20p
			50	38	VSII_hns_100mm_50ohm_38.s20p
		300	45	36	VSII_hns_300mm_45ohm_36.s20p
			50	38	VSII_hns_300mm_50ohm_38.s20p

# ■ Provided Touchstone list



• Connector only model



• Cable only model

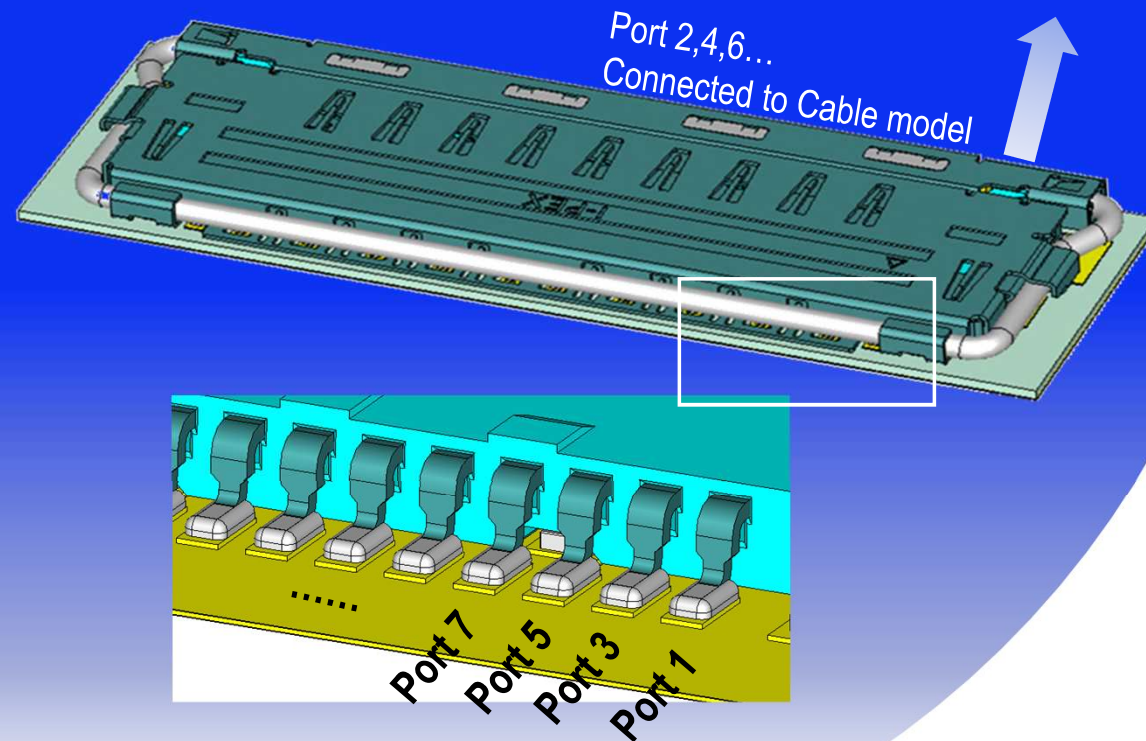


Model Type	Pin assignment	Port Zo (Ohm)			File name
Connector only	All Signal	45			VSII_con_45ohm.s20p
		50			VSII_con_50ohm.s20p

Model Type	Pin assignment	Cable Length (mm)	Cable Zo (Ohm)	AWG	File name
Cable only	-	100	45	36	MCX_100mm_45ohm_36.s2p
			50	38	MCX_100mm_50ohm_38.s2p
		300	45	36	MCX_300mm_45ohm_36.s2p
			50	38	MCX_300mm_50ohm_38.s2p

# ■ Simulation Results Example

## 【Electromagnetic Simulation】



### Simulation conditions

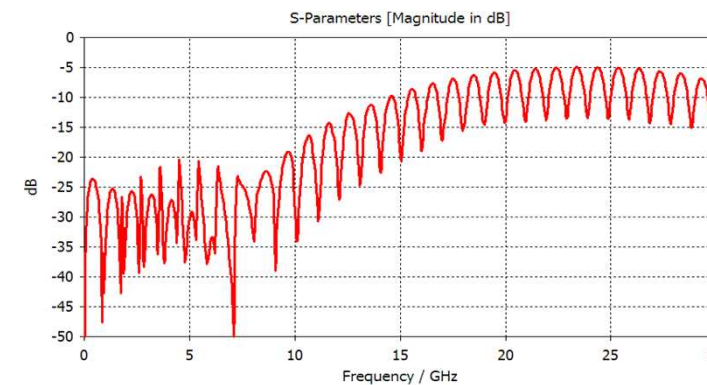
- Frequency : up to 30GHz
- Pin Assign : GSSGSSGSSG
- Differential Port Impedance : **85 Ohm**

### Used Model

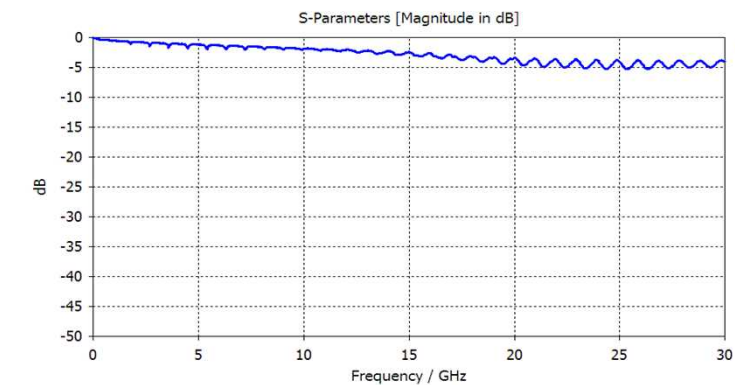
- Connector (VSII\_con\_45ohm.s20p)
- Cable (MCX\_100mm\_45ohm\_36.s2p)

## ■ S-Parameter (Mixed Mode)

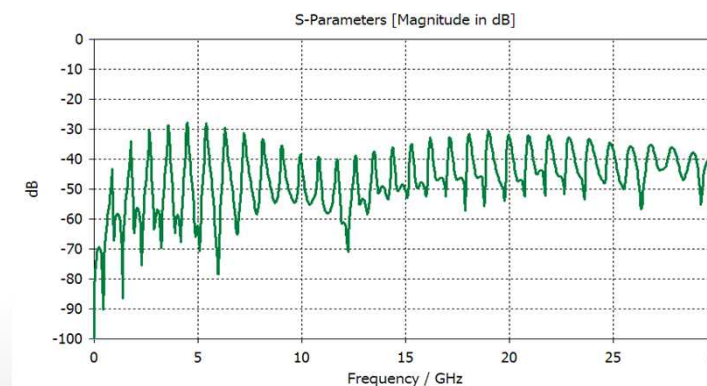
### Return Loss



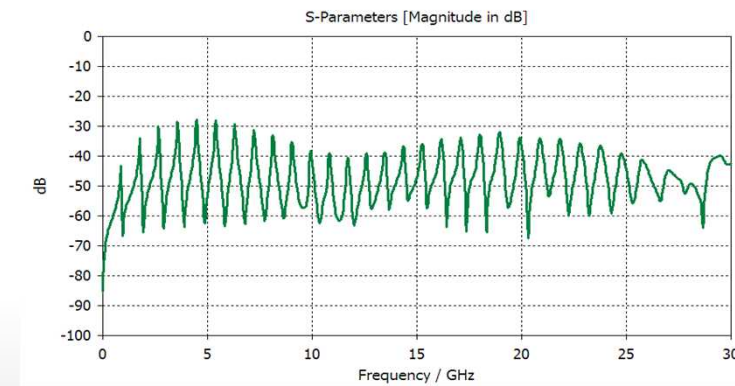
### Insertion Loss



### Near End Crosstalk

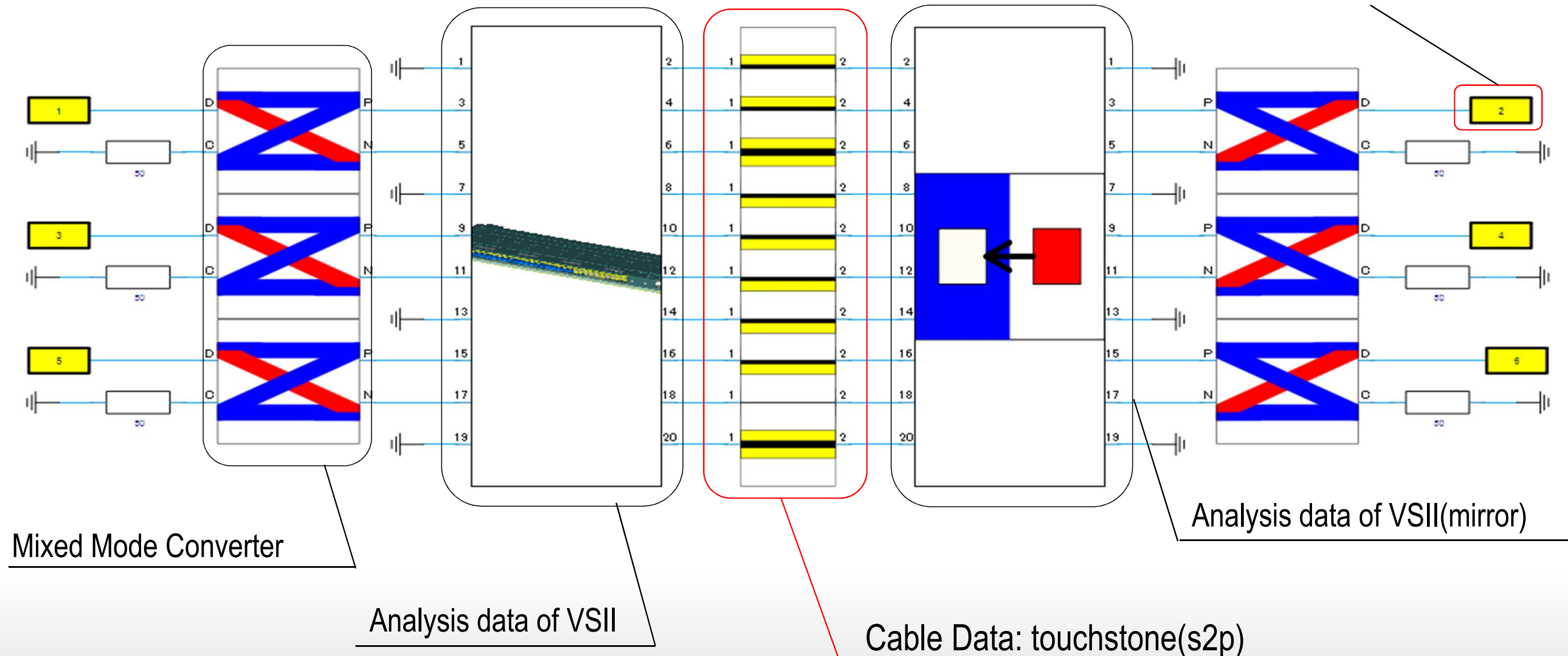


### Far End Crosstalk



# ■ Circuit simulation Example

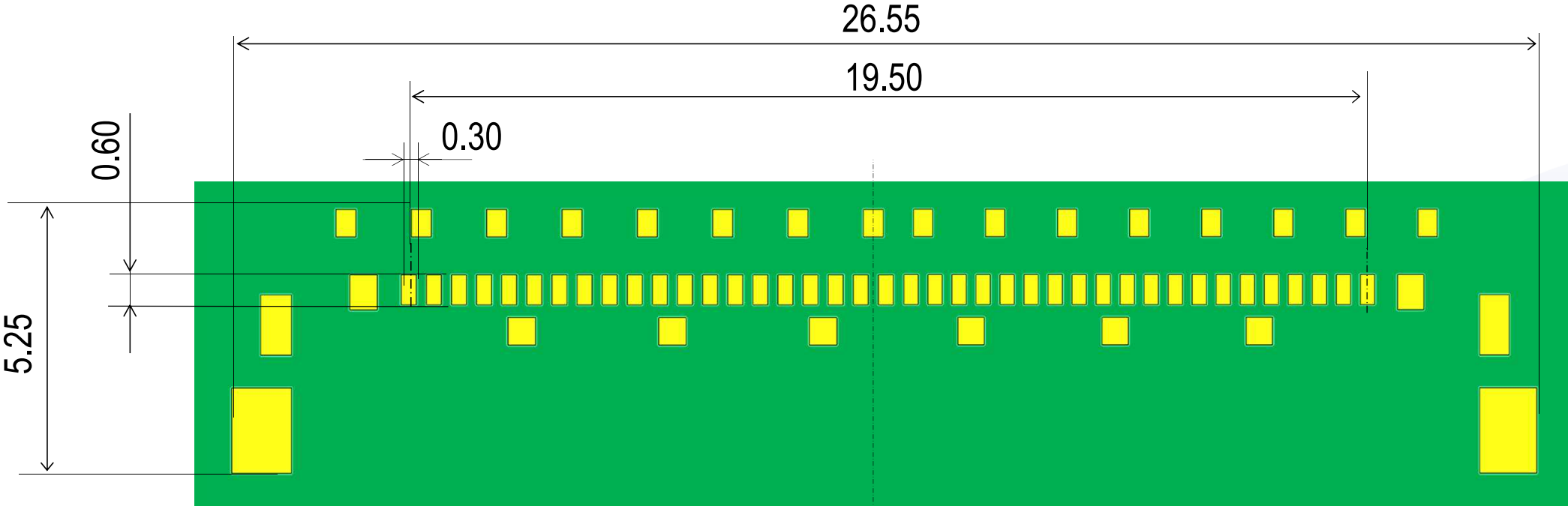
- Used software  
CST Microwave Studio 2019



# Footprint Example



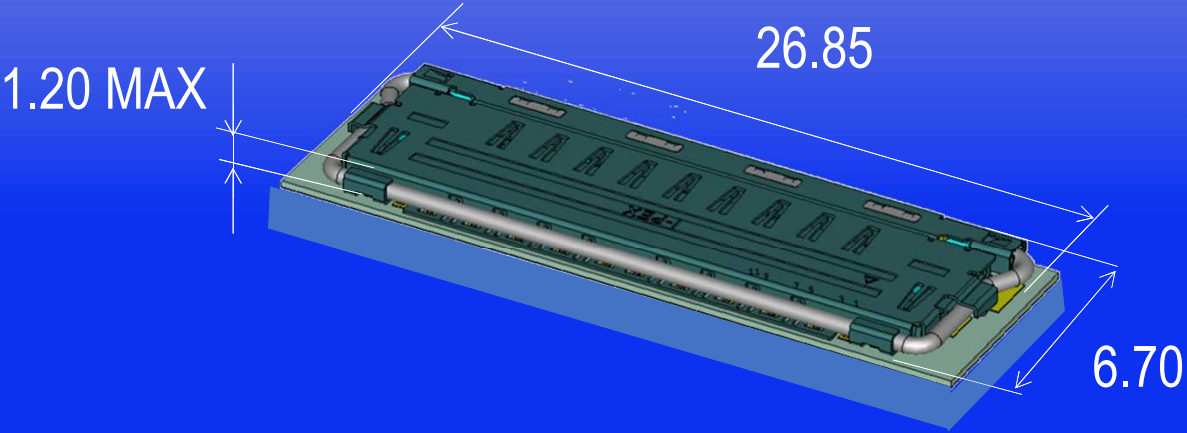
Footprint pattern size : 40p (mm)



Connector size : 40p (mm)

For the detail and other pin counts : Please refer to I-PEX web-site.

PCB Stackup		
	Material	Thickness (mm)
TOP RESIST	Solder Mask	0.02
TOP LAYER	Copper	0.04
INSULATOR	Low Dk Material	0.2
BOTTOM LAYER	Copper	0.04
BOTTOM RESIST	Solder Mask	0.02





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